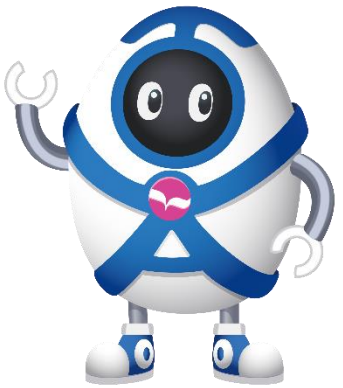
FY2025 3Q
Business Results

February 6, 2026



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FY2025 3Q Summary

¥100M

Orders	Net Sales	Operating Profit	Ordinary Profit	Net Profit
¥446.5	¥369.3	¥36.8	¥36.9	¥26.2
YoY +20.1%	YoY -5.9%	YoY -43.5%	YoY -47.8%	YoY -49.0%

Orders

・Orders are strong, mainly for AI and data center-related applications such as memory and advanced packaging.
・Orders for 3Q amounted to ¥196.2, marking the second-highest level on a quarterly basis on record.

Net Sales

・Net sales decreased YoY due to the impact of U.S. tariffs in 1Q and weak investment for automotive semiconductor applications.
・Due to improved customer utilization rates, net sales of TSS (Total Solution Service) increased.

Profit

・In addition to the decrease in net sales, profit decreased due to changes in product mix and the impact of additional costs associated with initial shipment.

FY2025 3Q Consolidated Financial Results

¥100M

	FY2024 3Q Results	FY2025 3Q Results	Variance	YoY
Net Sales	392.5	369.3	-23.2	-5.9%
Operating Profit	65.2	36.8	-28.3	-43.5%
Operating Margin	16.6%	10.0%	–	-6.6pt
Ordinary Profit	70.8	36.9	-33.8	-47.8%
Net Profit	51.5	26.2	-25.2	-49.0%

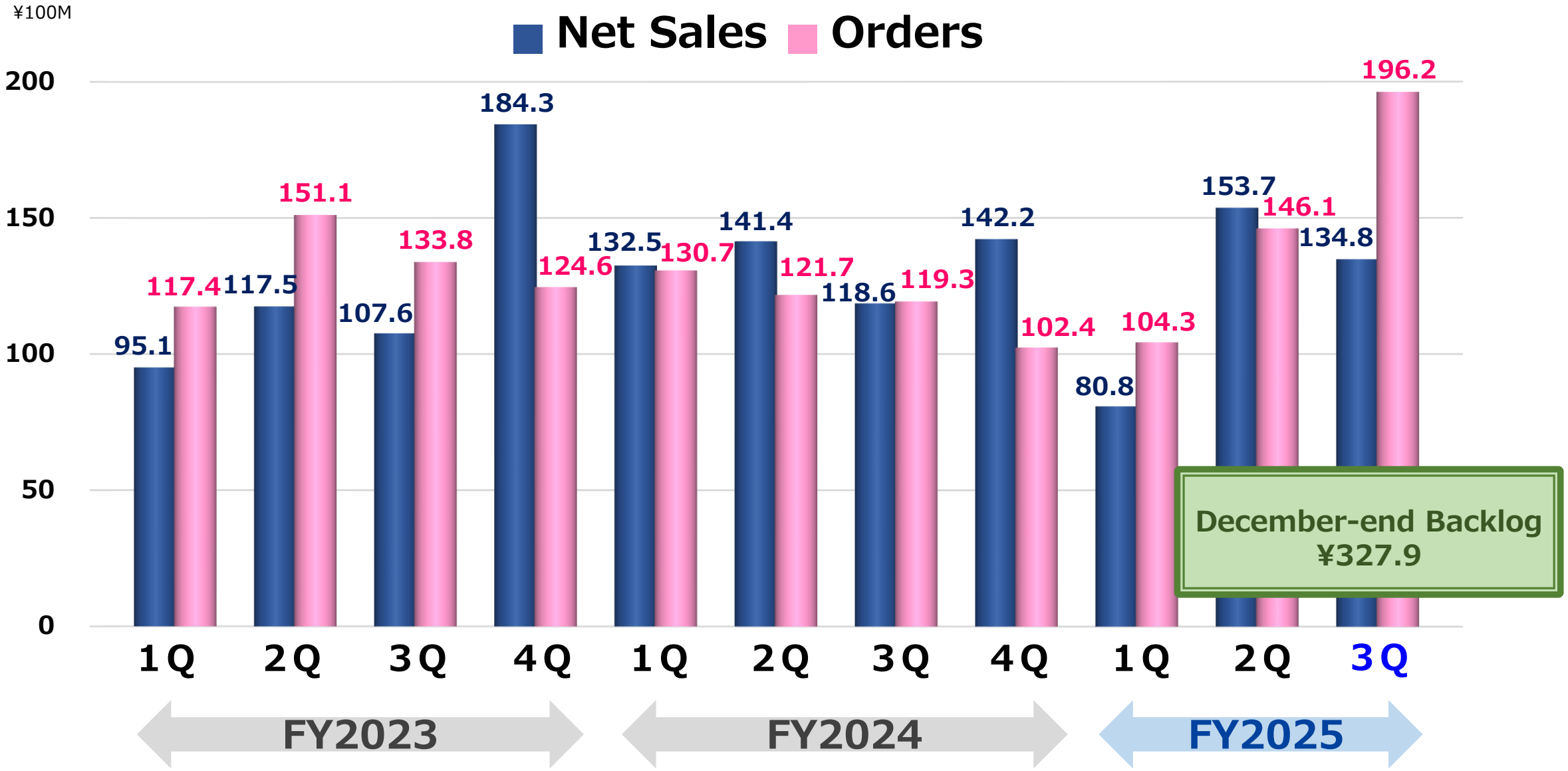
※Net Profit= Profit attributable to owners of parent

FY2025 3Q Net Sales by Business Segment

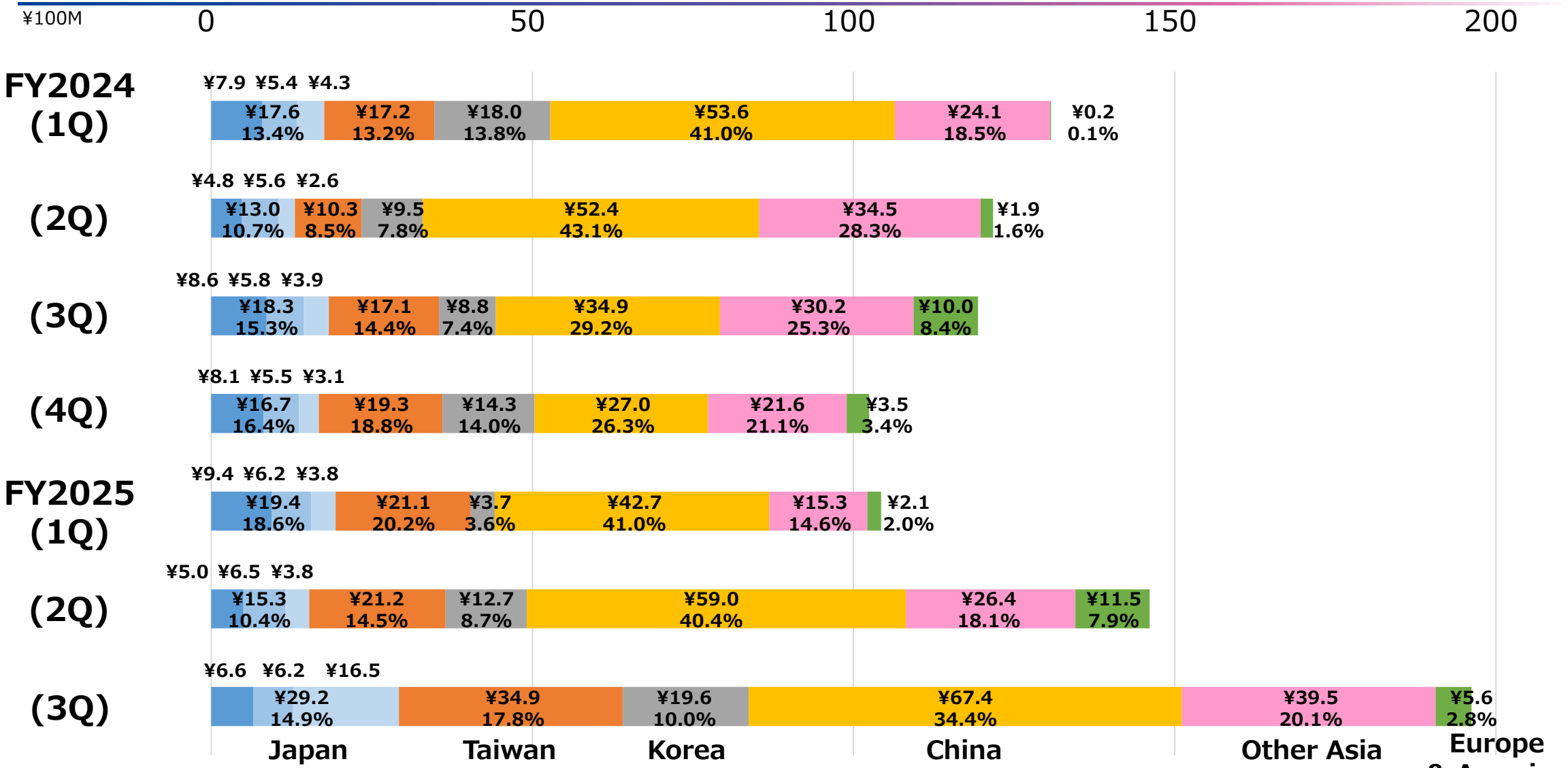
¥100M

	FY2024 3Q Results	FY2025 3Q Results	Variance	YoY
Net Sales	392.5	369.3	-23.2	-5.9%
Semiconductor	292.7	268.1	-24.6	-8.4%
Medical Device	17.3	18.6	+1.3	+7.8%
New Business	68.4	71.3	+2.8	+4.1%
Laser	14.1	11.2	-2.8	-20.0%

Net Sales and Orders Trend

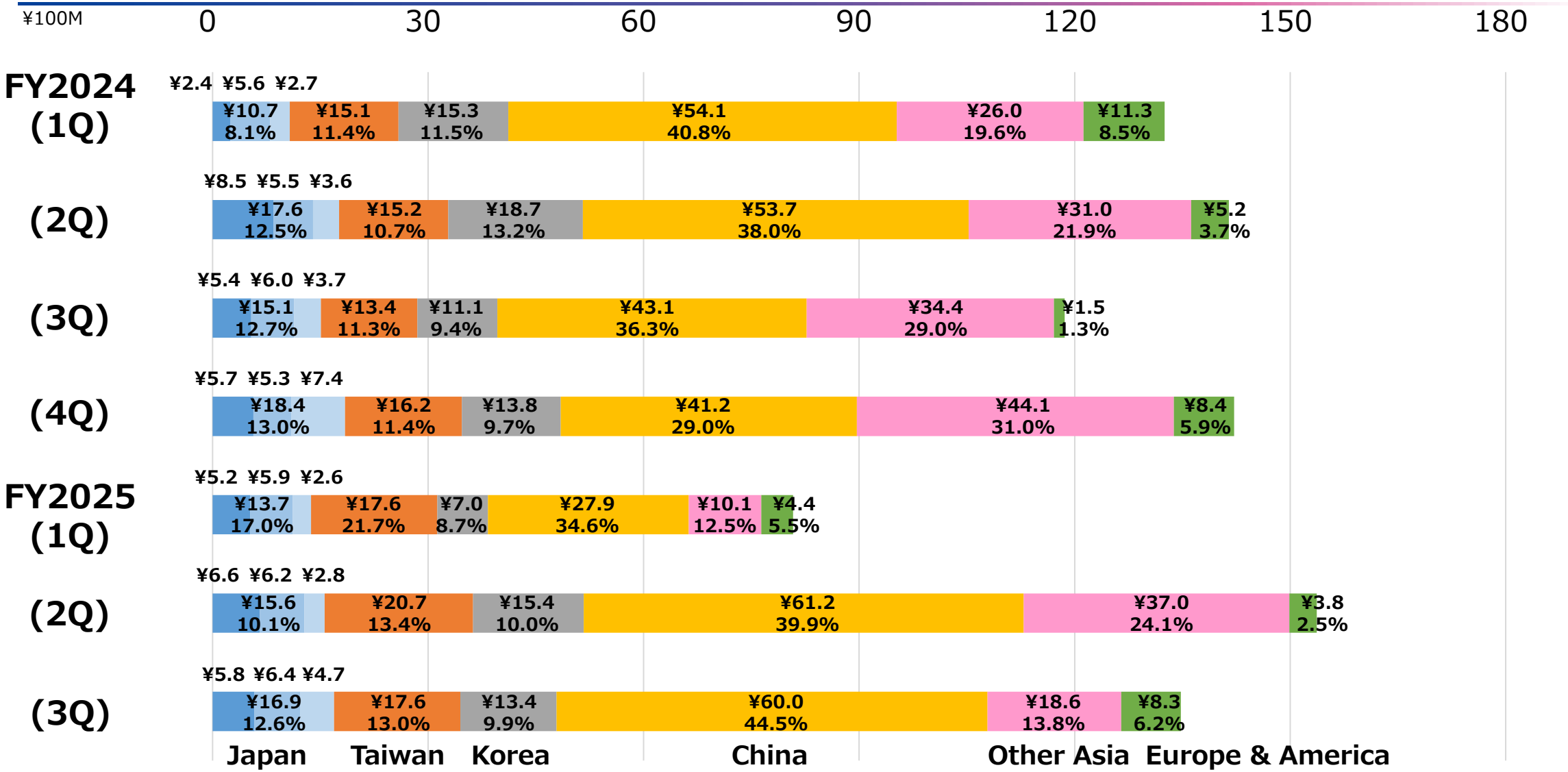


Trend of Regional Order Composition Ratio (Destination-Based)



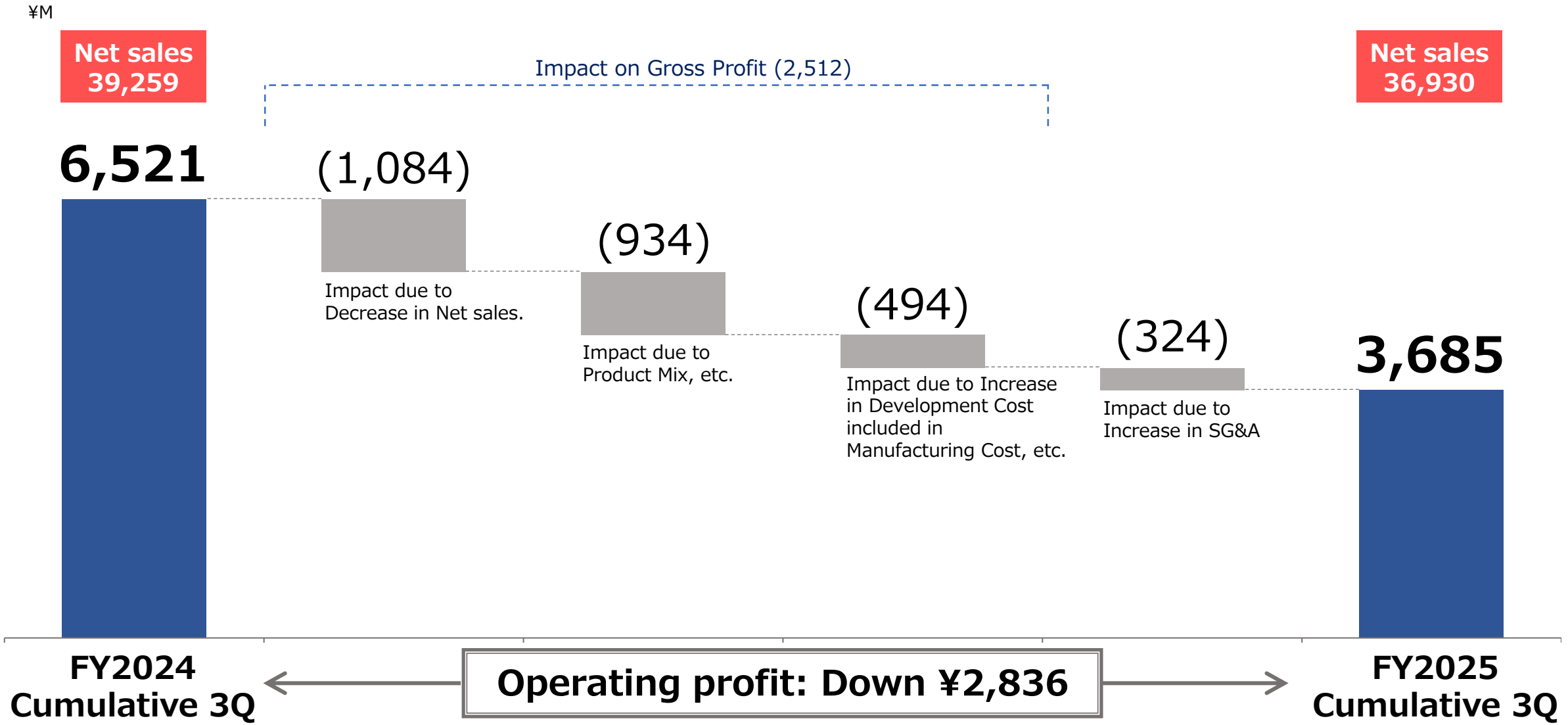
※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

Trend of Regional Sales Composition Ratio (Destination-Based)



※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

FY2025 3Q Operating Profit Variance Analysis（YoY）



※Yen amounts are rounded down to millions.

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Revision of full-year forecast

¥100M

	FY2025 Initial Forecast	FY2025 Revision Forecast	Compared to Initial Forecast
Net Sales	560.0	545.0	-15.0 (-2.7%)
Operating Profit	98.0	70.0	-28.0 (-28.6%)
Operating Margin	17.5%	12.8%	-4.7pt
Ordinary Profit	98.0	70.0	-28.0 (-28.6%)
Net Profit	68.6	49.5	-19.1 (-27.8%)

※Net Profit= Profit attributable to owners of parent

Background to the Revision

Net Sales

- Mass production investments in memory were delayed compared with initial forecast.
- The proportion of orders for evaluation equipment with long lead times increased.

Profit

- Changes in the customer mix for transfer equipment negatively impacted profit margins.
- Higher investments in evaluation equipment and first-unit orders for compression equipment had a temporary negative impact on profit margins.

FY2025 Forecast

¥100M

Changed

	FY2024 Results	FY2025 Forecast			Variance	YoY
		3Q Results	4Q Forecast	FY		
Net Sales	534.7	369.3	175.7	545.0	+10.2	+1.9%
Operating Profit	88.8	36.8	33.2	70.0	-18.8	-21.2%
Operating Margin	16.6%	10.0%	18.9%	12.8%	-3.8pt	-
Ordinary Profit	94.0	36.9	33.1	70.0	-24.0	-25.5%
Net Profit	81.2	26.2	23.2	49.5	-31.7	-39.0%

※Net Profit= Profit attributable to owners of parent

FY2025 Forecast of Net Sales by Business Segment

¥100M

Changed

	FY2024 Results	FY2025 Forecast			Variance	YoY
		3Q Results	4Q Forecast	FY		
Net Sales	534.7	369.3	175.7	545.0	+10.2	+1.9%
Semiconductor	395.3	268.1	131.7	399.8	+4.5	+1.1%
Medical Device	22.6	18.6	6.4	25.0	+2.4	+10.7%
New Business	94.2	71.3	28.9	100.2	+5.9	+6.3%
Laser	22.6	11.2	8.8	20.0	-2.6	-11.4%

Market Outlook Going Forward

Orders

- Due to AI-related investments and memory shortages, orders for compression equipment are strong.
- Compression orders in 3Q reached a record high on a quarterly basis.
- From 4Q onward, investments in memory and advanced packaging, primarily in Taiwan and China, continued to be a key driver.

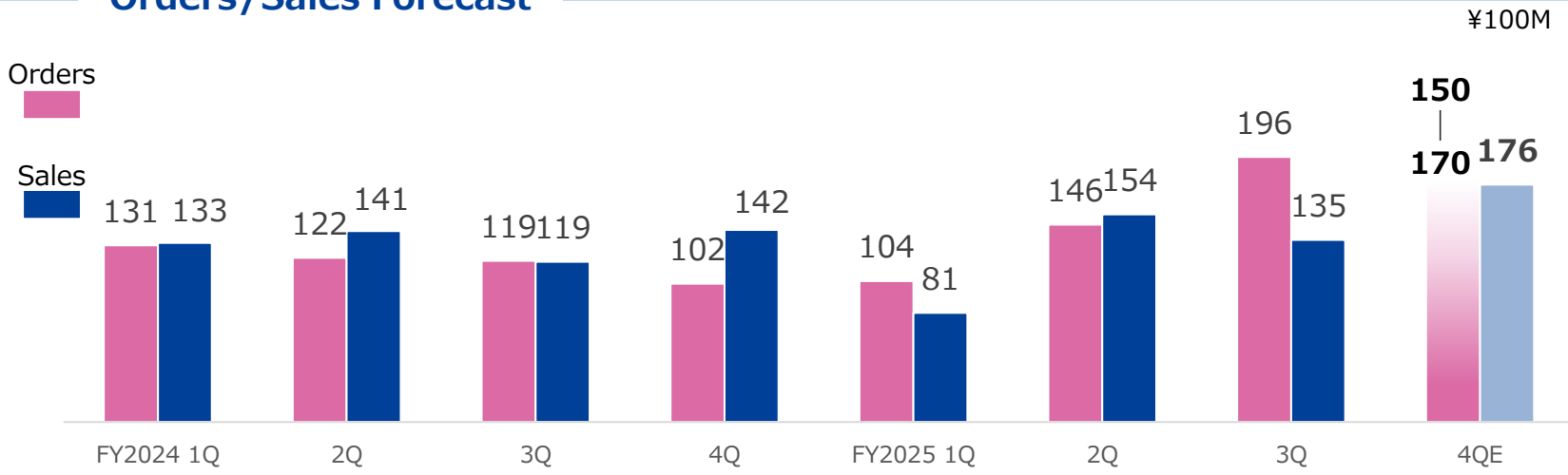
Sales

- Sales are expected to increase going forward, driven by growth in mass production orders.

Profit

- With the increase in orders for compression equipment, profit margins are expected to gradually improve.

Orders/Sales Forecast



Orders Forecast

¥100M

4Q
¥150－170

Profit & Loss Forecast

(Revised as of February 6, 2026)

¥100M

Net Sales	¥545.0
Operating Profit	¥70.0
Ordinary Profit	¥70.0
Net Profit	¥49.5

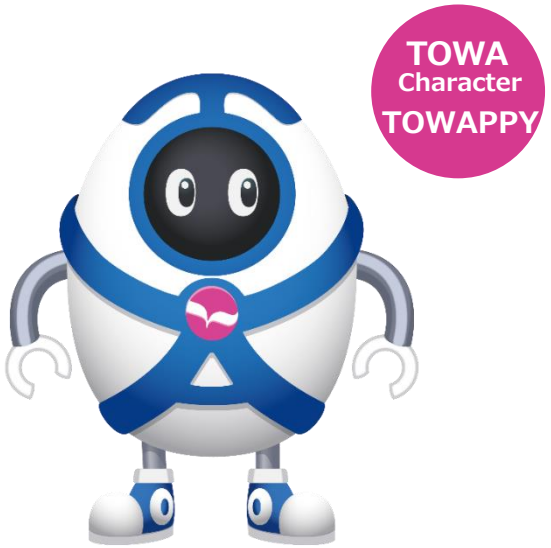
TOWA Vision 2032

「To the top of the world with change」

《Contact》
TOWA CORPORATION Corporate Planning Dept.
5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto 601-8105
Telephone number : 075-692-0251

Reference materials

Corporate Overview



Profile of TOWAPPY

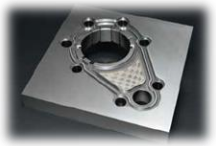
[1] Name: TOWAPPY
[2] Origin of the name:
Delivering happiness to the world from TOWA.
[3] Favorite word: Challenge!

Company name	TOWA CORPORATION
Business	Semiconductor Business, New Business, Medical Device Business, Laser Processing Machines Business
Address	5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto
Established	April 1979
Chairman & CEO	Hirokazu Okada
President Executive Officer	Muneo Miura
Number of Employee	2,209 (consolidated) [as of December 2025]
Paid-in Capital	8.9 billion yen
Code Number	6315

TOWA's Business

New Business

・TSS
(Total Solution Service)
・Tools for precision process,
Consignment processing
・Fine process
・Coating



Consignment processing

Remodeling, Repair,
Preventative Maintenance

Fine process
technology

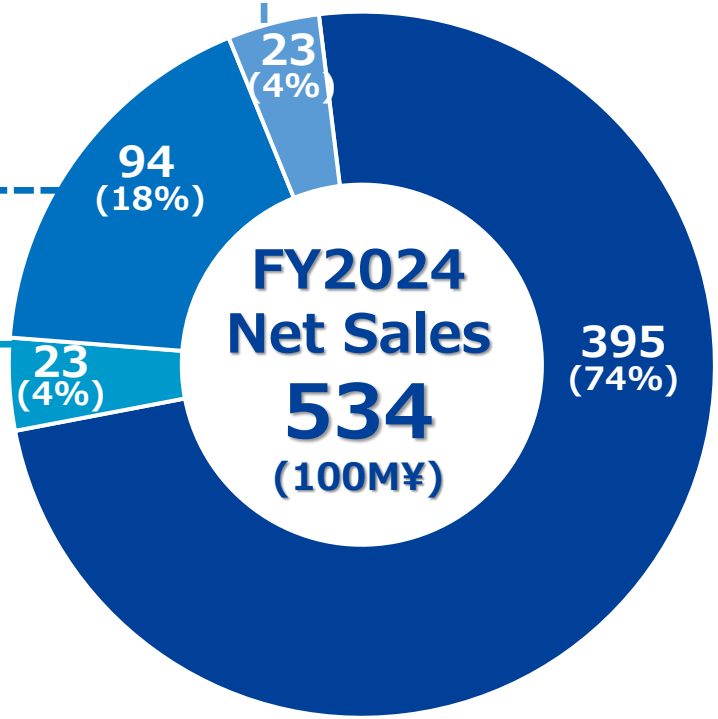
Tool (end mill)

Laser Processing Machines Business

・Laser Trimmer
・Wafer Marker
・Laser Welder

Laser Trimmer
Model SL432R

Wafer Marker
Model SL473GS3



Medical Device Business

・Fine plastic products
・Medical products

Component for IV drip

Component for syringe

Semiconductor Business

・Precision molds, Molding equipment and Singulation equipment for semiconductor manufacturing

Transfer Mold

Molding Equipment
Model PMC 2030-D

Compression Mold

Molding Equipment
Model CPM 1080

Semiconductor Manufacturing Process

Front-end process

TOWA LASER FRONT
Wafer Marker (Hard)

oxidation

Thin film forming

Photoresist coating

Dry Etching

Ion implantation

TOWA LASER FRONT
Wafer Marker (Soft)

Electrode formation

Wafer test

Back-end process

Dicing

Mounting

Bonding

TOWA

Molding

Chips are molded by resin.

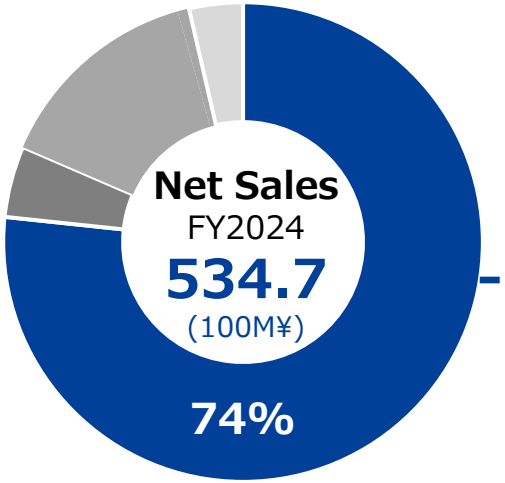
Singulation

Each chip is cut out from a frame.

After inspection process,

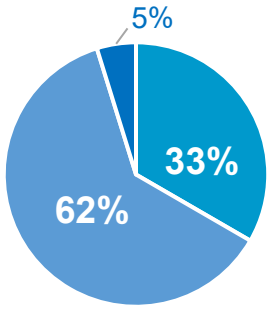
Complete!

Semiconductor Business



Semiconductor Business

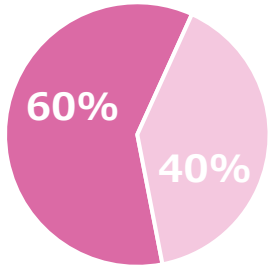
395.3 (100M¥)



- Precision molds
- Molding equipment
- Singulation equipment

Molding equipment and Precision molds

375.9 (100M¥)

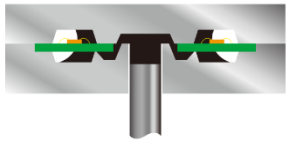


- Transfer equipment and molds
- Compression equipment and molds

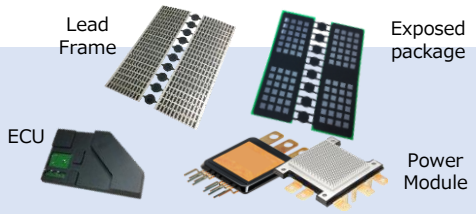
Molding

Transfer Molding

Molding method in which the resin is melted in a pot and filled into a cavity to be hardened.



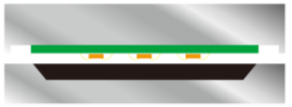
Transfer

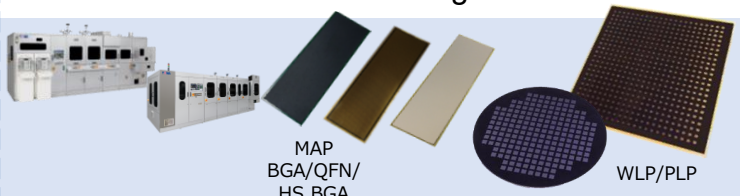


Work size (Max.): 100×300mm

Compression molding

Molding method in which the resin is placed directly into the cavity, and then the workpiece is immersed into the cavity after the resin is melted for resin molding.



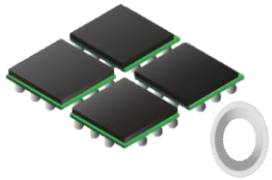


Compression

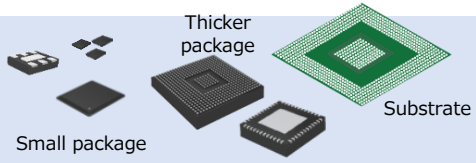
Work size (Max.): 660×620mm

Singulation

Dicing and storing process for molded products by transfer or compression molding methods.



Singulation



Package size (Min.): 1×1 mm

New Business

Create new market and develop new business

TSS Business

(Total Solution Service)

Propose kinds of solutions such as after sales service, refurbishment, fixing of TOWA's semiconductor manufacturing equipment and used equipment sales.

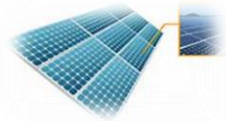
All molding process all over the world to TOWA!!

- **Life Extension Program**
- **Used equipment sales**
- **Prevention & Upkeep (year to year basis contract)**
- **Parts provision**
- **Training Center**

Coating Business

Apply TOWA's original mold surface processing technologies to medical products and domestic articles.

Expand share in pill pressing machine



Expand share in glass products

Nano tech Business

Apply ultra precise and fine processing technology used in ultra precision mold processing to medical and automobile fields.

Develop products in bacteria cultivation business

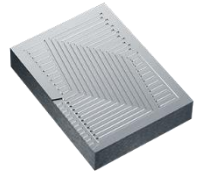
Develop lenses for Head Up Display

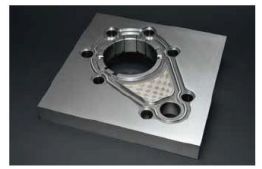
Develop lens for air picture projection

Tooling Business

Sell tools developed in house and incorporate TOWA's know-how as a mold manufacturer.

CBN・Ultra hard end mill





Processing by undertaking customer order

Fusion of a 3D printer and TOWA's too

Medical Device Business

Company Name	BANDICK CORPORATION
Business	Manufacturing of medical plastic molded products Assembly of medical equipment
Address	596-146 Shimojo Minamiwari, Tatsuoka-cho, Nirasaki-shi, Yamanashi
Acquisition Date	November 18, 1983

President & CEO	Toshihiro Terauchi
Number of Employees	95 (as of December 2025)

Main Products

Medical plastic molded product

Plastic molding process using ultra-precision mold technology and proprietary technology

Assembling and production in a clean room

Laser processing machine business

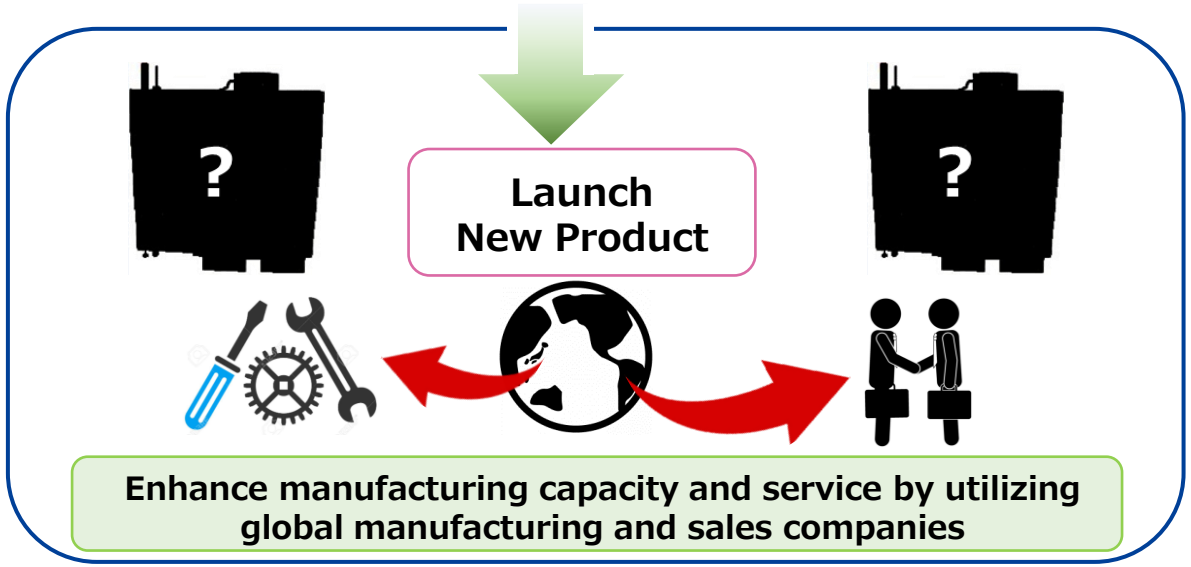
Company Name	TOWA LASERFRONT Corporation
Business	Development, Design, Manufacturing, Sales and Maintenance of Laser & Laser Processing machines
Address	1120, Shimokuzawa, Chuo-ku, Sagamihara-shi, Kanagawa
Acquisition Date	August 1, 2018
President & CEO	Noboru Hayasaka
Number of Employees	106 (as of December 2025)

Main Products

Laser Trimmer	Wafer Marker	Laser Welder
		

Combine laser related technology and back-end semiconductor technology to create new market

TOWA × LASERFRONT



Enhance manufacturing capacity and service by utilizing global manufacturing and sales companies

Factories

● TOWA ● Affiliated Companies

Korea

● TOWA KOREA Co., Ltd.
» Manufacturing of equipment, precision mold and component

● TOWA FINE Co., Ltd.
»Manufacturing of blade

China

● TOWA (Suzhou) Co., Ltd.
»Manufacturing of equipment and precision mold

● TOWA (Nantong) Co., Ltd.
»Manufacturing of equipment and precision mold

Malaysia

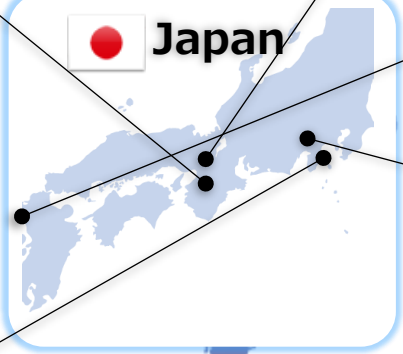
● TOWAM Sdn. Bhd.
»Manufacturing of equipment

● TOWA TOOL Sdn. Bhd.
»Manufacturing of mold

Kyoto (Kyoto-shi)

● Headquarters/Factory
»Develop/manufacture of equipment and precision mold

Japan



Kanagawa (Sagamihara-shi)

● TOWA LASERFRONT Corporation
»Develop/manufacture of laser & laser processing machines

Kyoto (Ujitawara-cho)

● Kyoto East Plant
»Manufacturing of mold

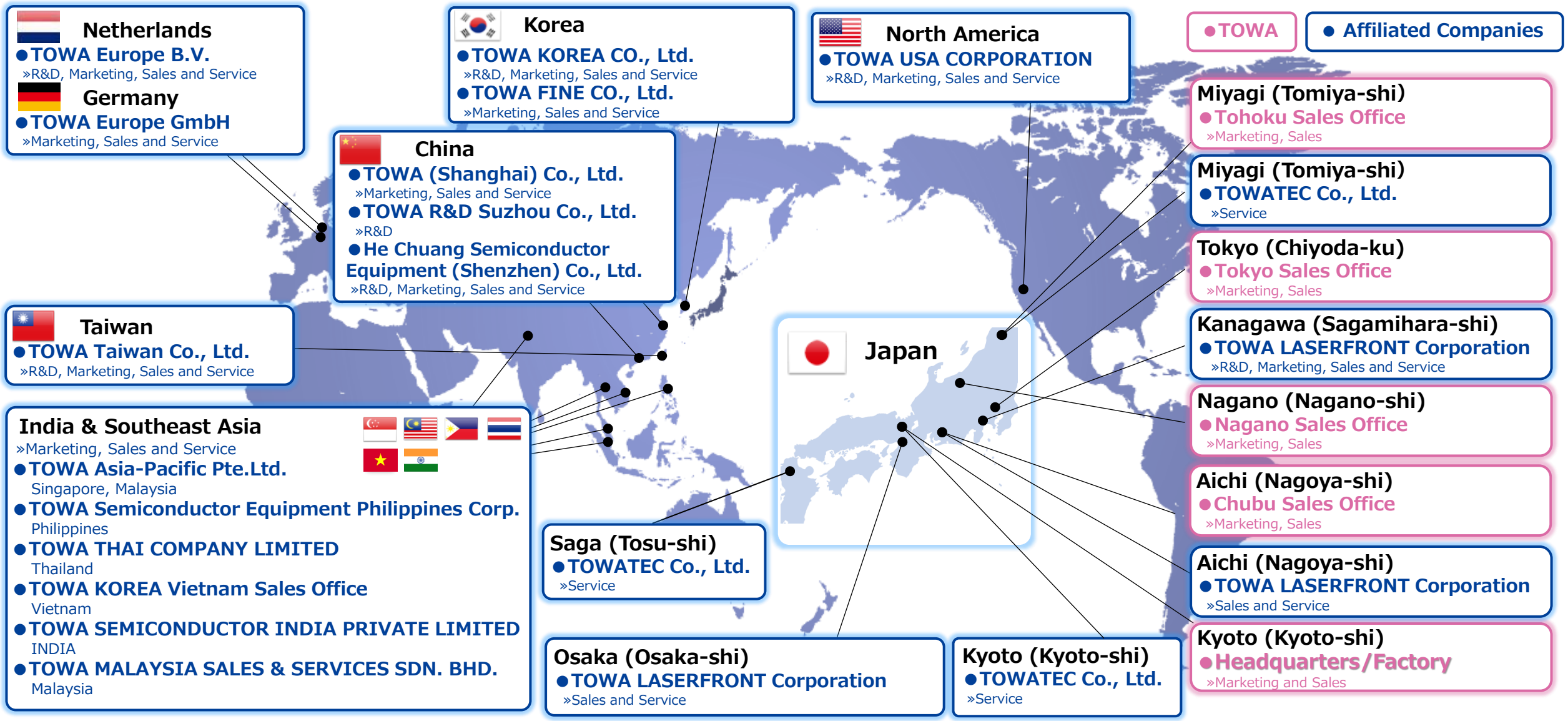
Saga (Tosu-shi)

● Kyushu Work
» Manufacturing of mold

Yamanashi (Nirasaki-shi)

● BANDICK Corporation
»Manufacturing of fine plastic products

Sales/Service facility



● TOWA ● Affiliated Companies

Netherlands
- ● TOWA Europe B.V.
  »R&D, Marketing, Sales and Service

Germany
- ● TOWA Europe GmbH
  »Marketing, Sales and Service

Korea
- ● TOWA KOREA CO., Ltd.
  »R&D, Marketing, Sales and Service
- ● TOWA FINE CO., Ltd.
  »Marketing, Sales and Service

North America
- ● TOWA USA CORPORATION
  »R&D, Marketing, Sales and Service

China
- ● TOWA (Shanghai) Co., Ltd.
  »Marketing, Sales and Service
- ● TOWA R&D Suzhou Co., Ltd.
  »R&D
- ● He Chuang Semiconductor Equipment (Shenzhen) Co., Ltd.
  »R&D, Marketing, Sales and Service

Taiwan
- ● TOWA Taiwan Co., Ltd.
  »R&D, Marketing, Sales and Service

India & Southeast Asia
»Marketing, Sales and Service
- ● TOWA Asia-Pacific Pte.Ltd.
  Singapore, Malaysia
- ● TOWA Semiconductor Equipment Philippines Corp.
  Philippines
- ● TOWA THAI COMPANY LIMITED
  Thailand
- ● TOWA KOREA Vietnam Sales Office
  Vietnam
- ● TOWA SEMICONDUCTOR INDIA PRIVATE LIMITED
  INDIA
- ● TOWA MALAYSIA SALES & SERVICES SDN. BHD.
  Malaysia

Japan

Saga (Tosu-shi)
- ● TOWATEC Co., Ltd.
  »Service

Osaka (Osaka-shi)
- ● TOWA LASERFRONT Corporation
  »Sales and Service

Kyoto (Kyoto-shi)
- ● TOWATEC Co., Ltd.
  »Service

Miyagi (Tomiya-shi)
- ● Tohoku Sales Office
  »Marketing, Sales

Miyagi (Tomiya-shi)
- ● TOWATEC Co., Ltd.
  »Service

Tokyo (Chiyoda-ku)
- ● Tokyo Sales Office
  »Marketing, Sales

Kanagawa (Sagamihara-shi)
- ● TOWA LASERFRONT Corporation
  »R&D, Marketing, Sales and Service

Nagano (Nagano-shi)
- ● Nagano Sales Office
  »Marketing, Sales

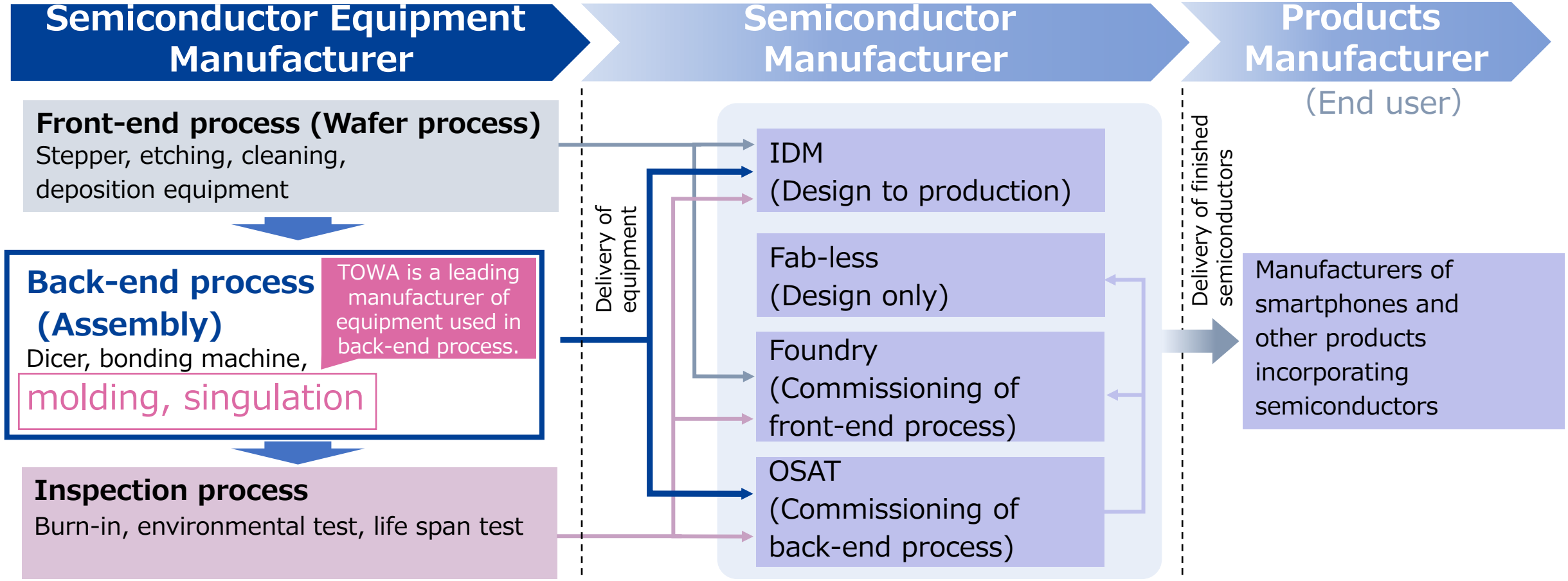
Aichi (Nagoya-shi)
- ● Chubu Sales Office
  »Marketing, Sales

Aichi (Nagoya-shi)
- ● TOWA LASERFRONT Corporation
  »Sales and Service

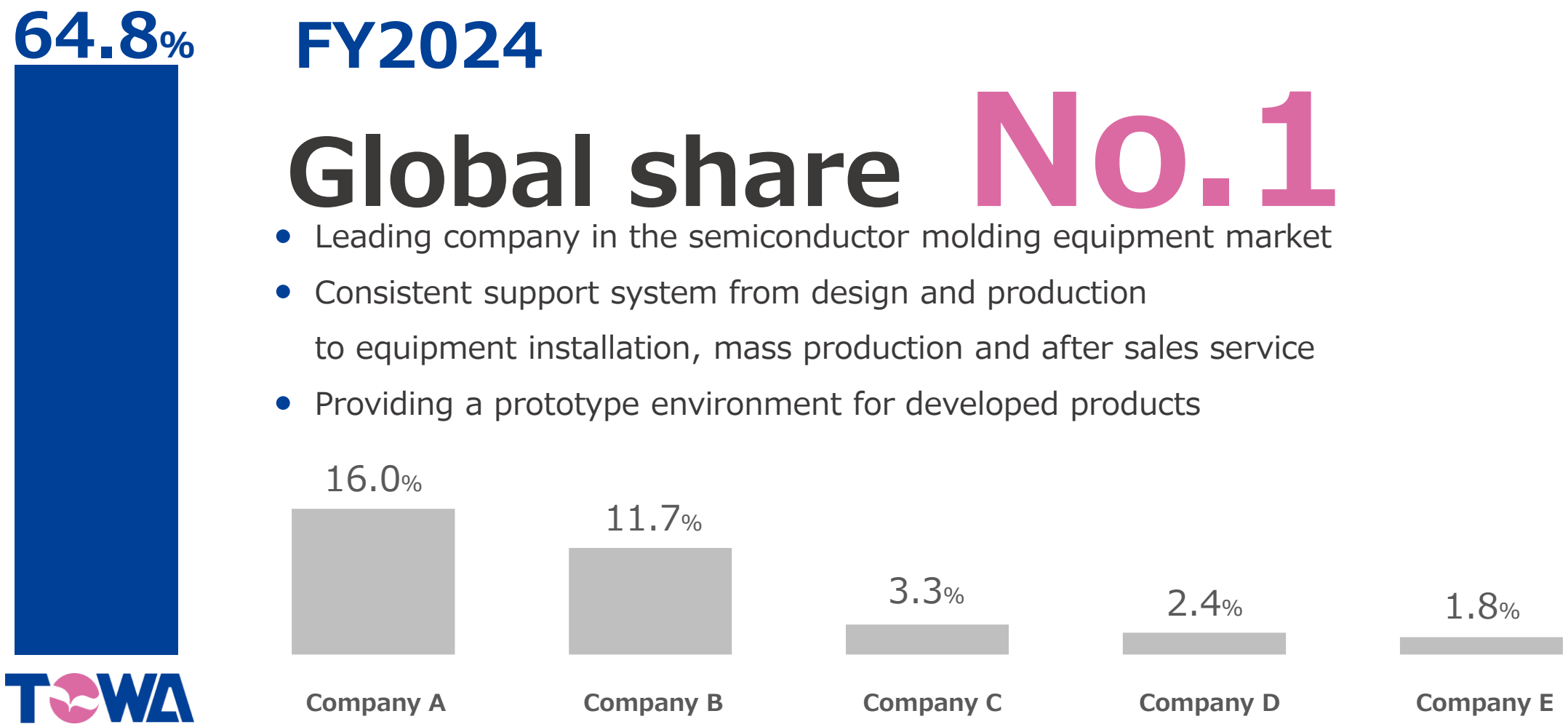
Kyoto (Kyoto-shi)
- ● Headquarters/Factory
  »Marketing and Sales

TOWA Group's Position in Semiconductor Manufacturing

Semiconductor equipment manufacturers can be classified as those producing specialized equipment for wafer (front-end) process, assembly (back-end) process, or inspection process, which they provide to semiconductor manufacturers. The semiconductors these manufacturers produce with this equipment are further supplied to downstream manufacturers who incorporate these semiconductors into their own products. The TOWA Group is a manufacturer of semiconductor equipment used in the back-end process.

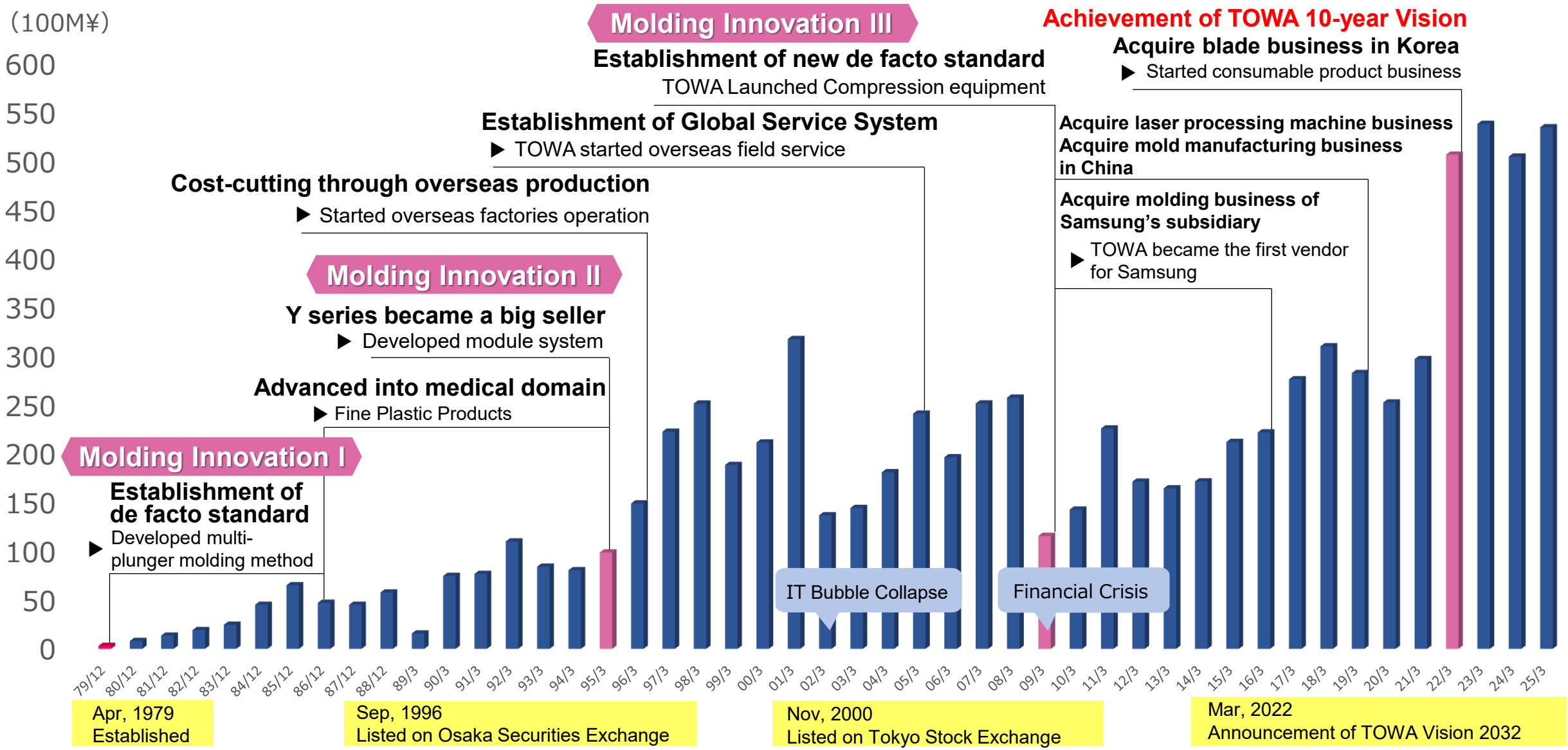


Global share of semiconductor molding equipment



*Created by our company based on data from TechInsights

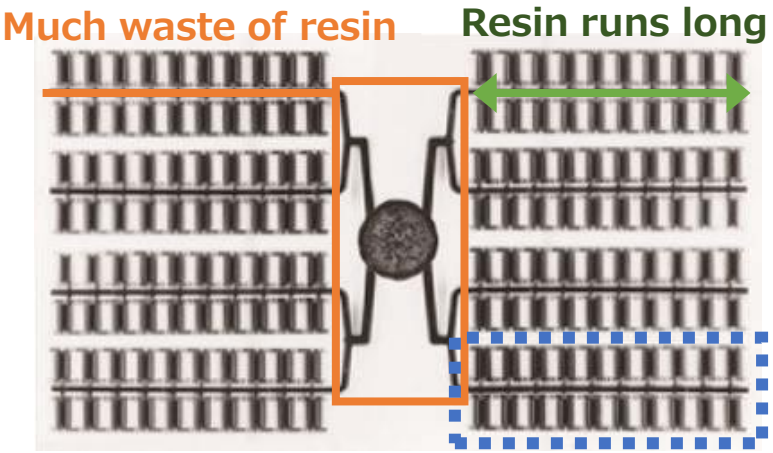
Progress of TOWA

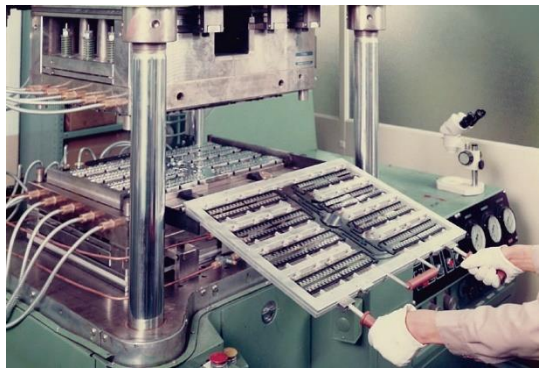


Molding innovation I (1979)

Conventional Mold

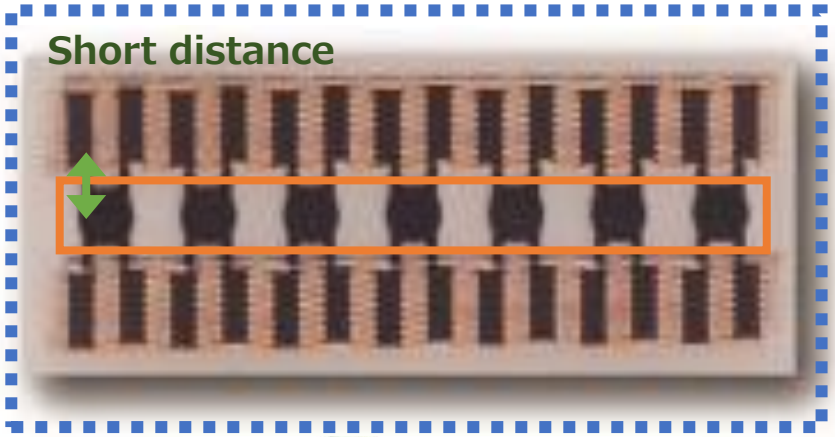
Manual molding by putting one palm size resin into the central pod. Resin runs long distance. Molding quality is not homogeneous. And much waste of resin.





Multi-Plunger Mold

Auto molding by putting finger size resins into several pods. This realized short runner, homogeneous molding quality and less waste of resin.



Molding innovation II (1995)

Module System (Y series)

Before the development of Module System,
Molding equipment was･･･

Each equipment is designed depends on what or how much it will manufacture.
Semiconductor manufacturers had to buy another equipment ,
when they want to manufacture another type of product or increase their product volume.

2 Module Connection

Module System enables to adjust press number!!

・Even you have only one Y series machine,
you can manufacture many types of products or increase your product volume.

4 Module Connection

Y series is sufficient to meet the needs of assembly subcontractor, to perform backend process bringing from IDM.

Semiconductor molding equipment is one of the strongest quality of TOWA.

Molding innovation III (2009)

Compression Molding Equipment

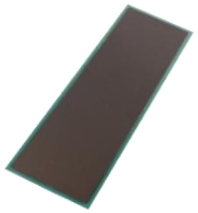
Independent compression molding technology has enabled to mold cutting-edge devices, and cut the cost significantly!!

The compression technology is unrivaled from its launch in 2009 because of the patent and technical difficulty.

Features

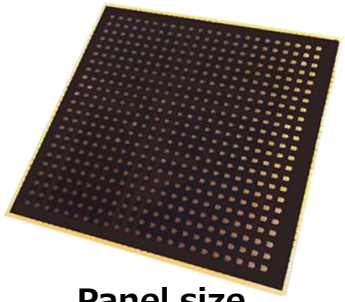
- 100% resin efficiency
  (CO2 emissions reduced by about 70%)
- Compression molding with no resin fluidity
  (reduce defective products)
- Most suitable for cutting-edge such as memory and 5G
- Applicable to both granular type and liquid type resin
- Applicable to both panel size and wafer size

Compression Equipment
Model PMC 2030-D



Substrate size
100×300mm

Wafer size
φ300mm



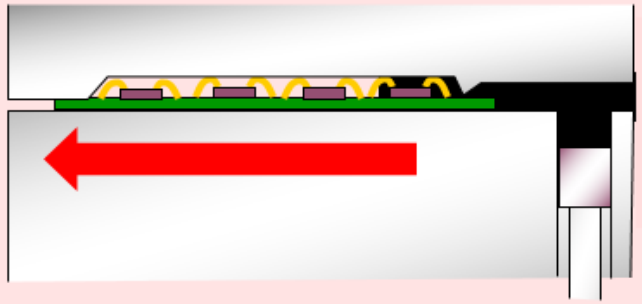
Panel size
600mm×600mm

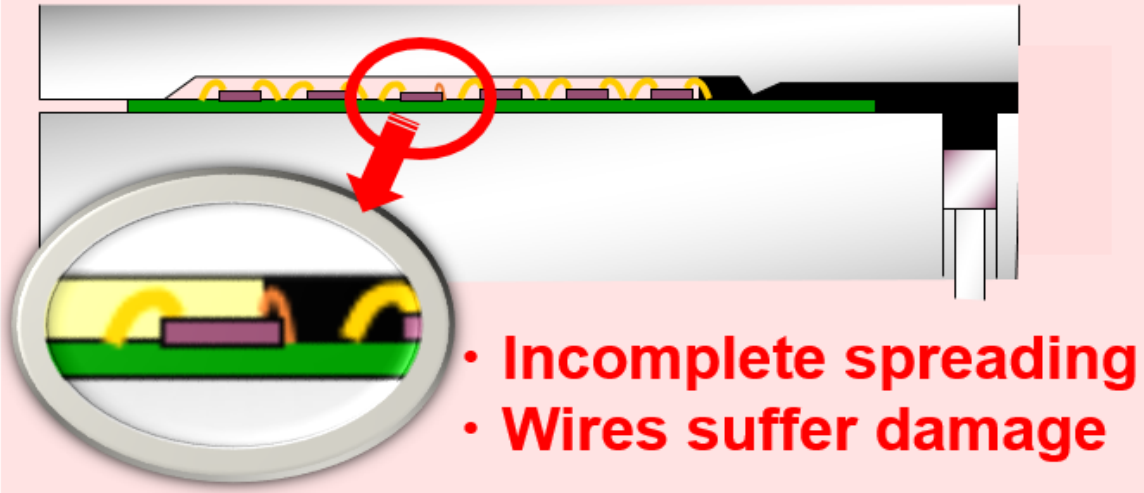
Encapsulation (Molding) Process

Transfer molding

Injecting resin type

Resin flows



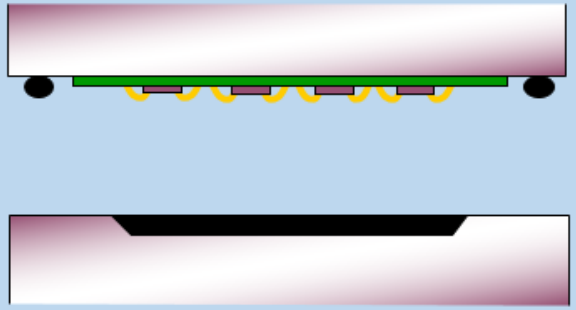


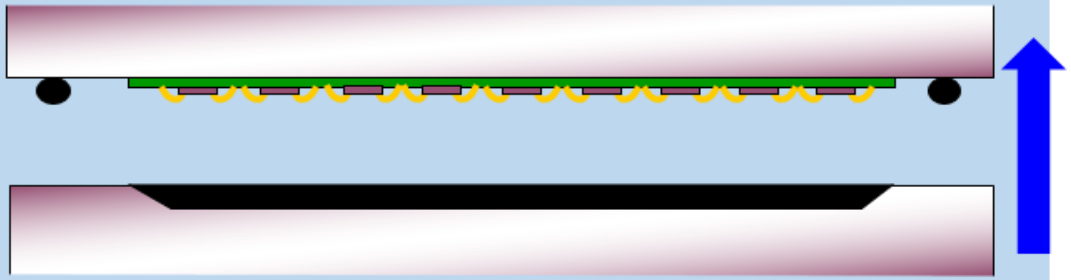
- Incomplete spreading
- Wires suffer damage

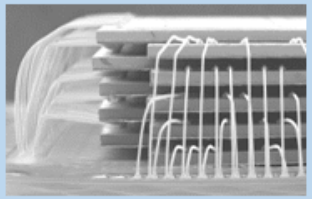
Compression molding

Compressing resin type

No Resin fluidity







- TOWA enabled large size panel molding
- No damage to products

Semiconductor Manufacturing Equipment Line-Up

～Compression Mold～

Compression Equipment
Model CPM 1180

Work max size：660×620mm

Compression Equipment
Model CPM 1080

Work max size：φ300mm, 320x320mm

Compression Equipment
Model PMC 2030-D

Work max size：100x300mm

～ Transfer Mold～

Transfer Equipment
Model YPM 1180

Work max size：100x300mm

Transfer Equipment
Model YPM1250-EPQ

Work max size：□150mm, 100x300mm

～ Singulation～

Singulation Equipment
Model FMS 4040

Work max size：100x300mm